2024-05-18 Contact Name Title - Contact Product-Env-Stewards Product-Enviro Compliance Authorized Representative* Title - Representative Phone - Contact* Product-Env-Stewards@onsemi.com Product-Env-Stewards@onsemi.com Phone - Representative* Email - Representative*	IPC ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.											
Company name* Company unique ID Unique ID Authority Response Date* 2024-05-18 Contact Name Title - Contact Phone - Contact* Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Produc	52-21.1					*						Mfg Informatio	n			
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Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Pr	semi											2024-0)5-18			
Title - Representative Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards ©nsemi.com Requester Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM FPAB30BH60B SPM3V CON 600V 30A SB 2024-05-18 CPA 15060.687 mg Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Mate Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	ontact Name			Title - Contact			1	Phone - Contact*				Email	Email - Contact*			
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Requester Item Number	athorized Represe	entative*	Title - Representative			1	Phone - Representative*				Email	Email - Representative*				
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or more information regarding material composition please refer to page 3			•.•	1 6 1												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
DBC	2416.55	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		966.6201	mg
			В	Nickel (Ni)	7440-02-0		24.1655	mg
			Supplier	Copper (Cu)	7440-50-8		1425.7645	mg
Die	45.2664	mg	Supplier	Silicon (Si)	7440-21-3		45.2664	mg
Die Attach	34.639	mg	Supplier	Silver (Ag)	7440-22-4		2.0783	mg
			Supplier	Tin (Sn)	7440-31-5		31.8679	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.6928	mg
Die Attach Epoxy	1.0764	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0323	mg
			Supplier	Silver (Ag)	7440-22-4		0.9149	mg
			Supplier	Proprietary	Proprietary Data		0.0538	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0753	mg
Lead Frame	2980.02	mg	Supplier	Silver (Ag)	7440-22-4		0.0298	mg
			Supplier	Iron (Fe)	7439-89-6		2.98	mg
			Supplier	Copper (Cu)	7440-50-8		2976.1162	mg
			Supplier	Phosphorus (P)	7723-14-0		0.894	mg
Mold Compound-Black	9449.18	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4-hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		283.4754	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		1889.8359	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		236.2295	mg
			Supplier	Carbon Black (C)	1333-86-4		94.4918	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		6945.147	mg
Plating	77.274	mg	Supplier	Tin (Sn)	7440-31-5		77.274	mg
Thermistor	4.47358	mg	Supplier	Silver (Ag)	7440-22-4		0.3579	mg
			Supplier	Tin (Sn)	7440-31-5		0.0761	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		1.1631	mg
			Supplier	Palladium (Pd)	7440-05-3		0.1521	mg
			В	Nickel (Ni)	7440-02-0		0.0313	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1		0.7695	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		1.9236	mg
Wire Bond - Al	50.409	mg	Supplier	Aluminum (Al)	7429-90-5		50.409	mg
Wire Bond - Cu	1.79769	mg	Supplier	Copper (Cu)	7440-50-8		1.7977	mg